

1. General description

Planar passivated guaranteed commutation triac in a SOT223 surface mountable plastic package for use in motor control circuits or with other highly inductive loads. This triac balances the requirements of commutation performance and gate sensitivity and is intended for interfacing with low power drivers, including micro controllers.

2. Features and benefits

- · 3Q technology for improved noise immunity
- Direct triggering from low power drivers and logic ICs
- High commutation capability with sensitive gate
- High immunity to false turn-on by dV/dt with sensitive gate
- · Planar passivated for voltage ruggedness and reliability
- Sensitive gate for easy logic level triggering
- Surface mountable package

3. Applications

- General purpose motor controls
- Small loads in washing machines
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids

4. Quick reference data

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| Table 1. Quic | k reference data | | | | | |
|---------------------|--|--|-----|-----|-----|------|
| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
| V _{DRM} | repetitive peak off- state voltage | | - | - | 600 | V |
| I _{T(RMS)} | RMS on-state current | full sine wave; T _{sp} ≤ 108 °C; <u>Fig. 1;</u> <u>Fig. 2; Fig. 3</u> | - | - | 1 | A |
| I _{TSM} | non-repetitive peak on- state current | full sine wave; T _{j(init)} = 25 °C; t _p = 16.7 ms | - | - | 11 | A |
| | | full sine wave; T _{j(init)} = 25 °C; t _p = 20 ms; <u>Fig. 4</u> ; <u>Fig. 5</u> | - | - | 10 | A |
| Tj | junction temperature | | - | - | 125 | °C |
| Static chara | cteristics | | | | | , |
| I _{GT} | gate trigger current | V _D = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; <u>Fig. 9</u> | - | - | 5 | mA |
| | | V _D = 12 V; I _T = 0.1 A; T2+ G-; T _j = 25 °C; <u>Fig. 9</u> | - | - | 5 | mA |

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| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|-----------------------|---------------------------------------|--|-----|-----|-----|------|
| | | V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 9</u> | - | - | 5 | mA |
| I _H | holding current | V _D = 12 V; T _j = 25 °C; <u>Fig. 11</u> | - | - | 6 | mA |
| V _T | on-state voltage | I _T = 2 A; T _j = 25 °C; <u>Fig. 12</u> | - | 1.2 | 1.5 | V |
| Dynamic ch | naracteristics | · | | | | |
| dV _D /dt | rate of rise of off-state voltage | V _{DM} = 402 V; T _j = 125 °C; (67% of V _{DRM}); exponential waveform; gate open circuit | 20 | - | - | V/µs |
| dl _{com} /dt | rate of change of commutating current | V_D = 400 V; T _j = 125 °C; I _{T(RMS)} = 1 A; dV _{com} /dt = 0.1 V/µs; gate open circuit | 5 | - | - | A/ms |
| | | V_D = 400 V; T _j = 125 °C; I _{T(RMS)} = 1 A; dV _{com} /dt = 20 V/µs; (snubberless condition); gate open circuit | 1 | - | - | A/ms |

5. Pinning information

| Table 2. | Pinning in | formation | | |
|----------|------------|--------------------------------|----------------------------|----------------|
| Pin | Symbol | Description | Simplified outline | Graphic symbol |
| 1 | T1 | main terminal 1 | 4 | |
| 2 | T2 | main terminal 2 | | G sym051 |
| 3 | G | gate | | syntost |
| 4 | mb | mounting base; connected to T2 | ∐1 ∐2 ∐3 SC-73 (SOT223) | |

6. Ordering information

| Table 3. Ordering infor | mation | | |
|-------------------------|---------|--|---------|
| Type number | Package | | |
| | Name | Description | Version |
| BTA204W-600D | SC-73 | plastic surface-mounted package with increased heatsink; 4 leads | SOT223 |

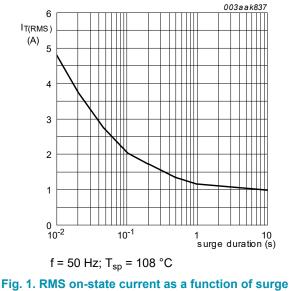


7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---------------------|-----------------------------------|--|-----|-----|------|
| V _{DRM} | repetitive peak off-state voltage | | - | 600 | V |
| I _{T(RMS)} | RMS on-state current | full sine wave; $T_{sp} \le 108 \text{ °C}$; <u>Fig. 1; Fig. 2;</u> Fig. 3 | - | 1 | A |
| | non-repetitive peak on- | full sine wave; $T_{j(init)}$ = 25 °C; t_p = 16.7 ms | - | 11 | А |
| | state current | full sine wave; $T_{j(init)}$ = 25 °C; t_p = 20 ms; Fig. 4; Fig. 5 | - | 10 | A |
| l ² t | I ² t for fusing | t _p = 10 ms; SIN | - | 0.5 | A²s |
| dl _T /dt | rate of rise of on-state current | I _G = 0.2 A | - | 100 | A/µs |
| I _{GM} | peak gate current | | - | 1 | А |
| P _{GM} | peak gate power | | - | 5 | W |
| P _{G(AV)} | average gate power | over any 20ms period | - | 0.5 | W |
| T _{stg} | storage temperature | | -40 | 150 | °C |
| Tj | junction temperature | | - | 125 | °C |



duration; maximum values

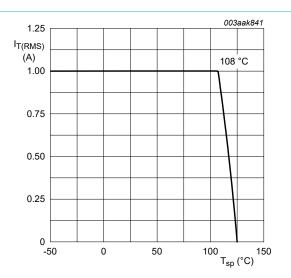
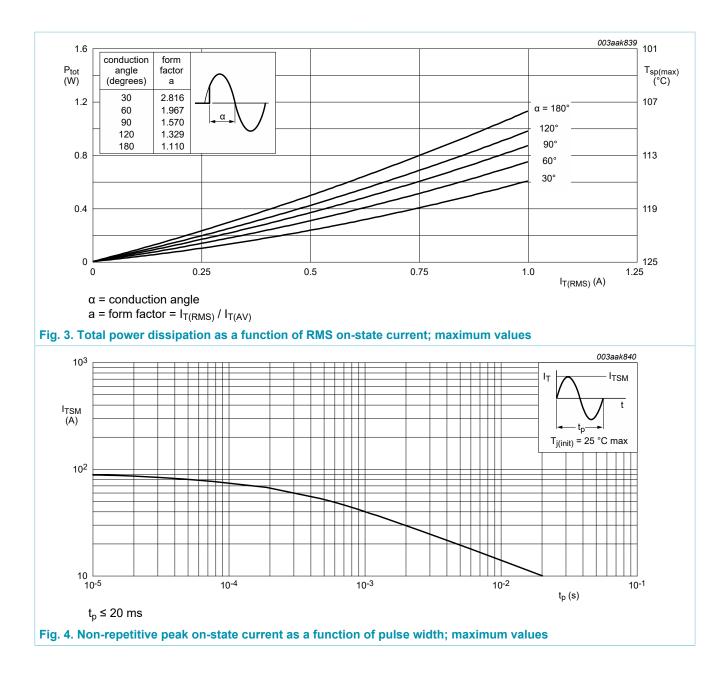


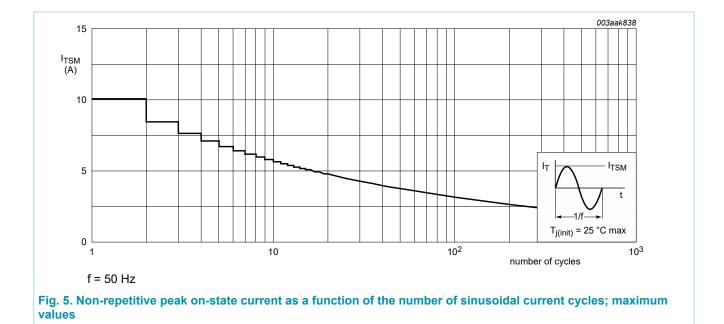
Fig. 2. RMS on-state current as a function of solder point temperature; maximum values

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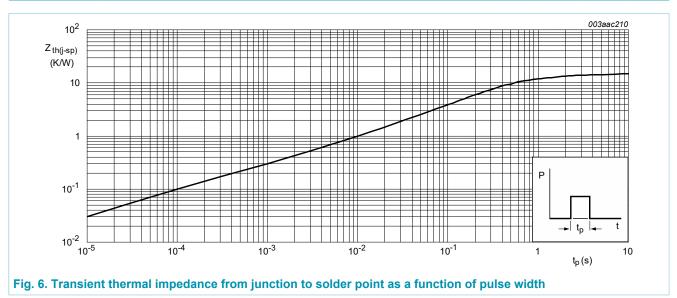
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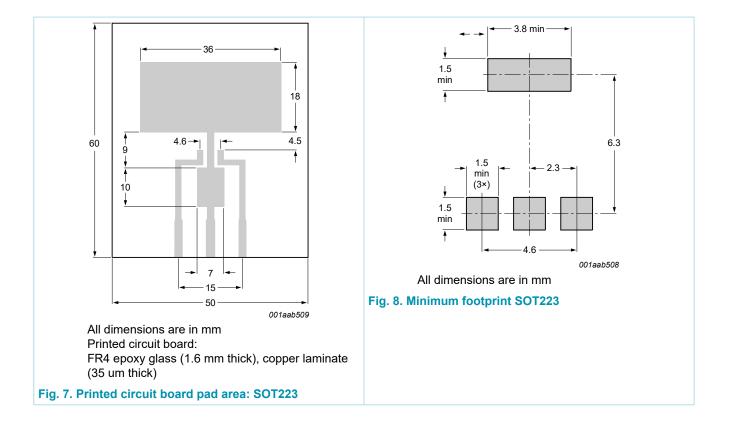
8. Thermal characteristics

| Table 5. Ther | mal characteristics | | | | | |
|-----------------------|--|--|-----|-----|-----|------|
| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
| R _{th(j-sp)} | thermal resistance from junction to solder point | full cycle or half cycle; <u>Fig. 6</u> | - | - | 15 | K/W |
| R _{th(j-a)} | thermal resistance from junction to | printed circuit board mounted: minimum pad area; Fig. 7 | - | 70 | - | K/W |
| | ambient free air | printed circuit board mounted: minimum footprint; Fig. 8 | - | 156 | - | K/W |



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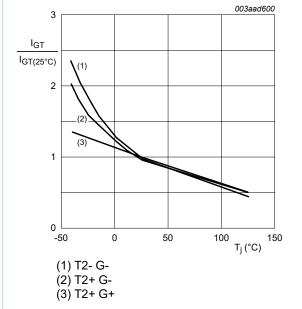
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9. Characteristics

| Symbol | Parameter | Conditions | Min | Тур | Мах | Unit |
|-----------------------|---------------------------------------|---|------|-----|-----|------|
| Static chara | acteristics | | | | | |
| I _{GT} | gate trigger current | V _D = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; <u>Fig. 9</u> | - | - | 5 | mA |
| | | V _D = 12 V; I _T = 0.1 A; T2+ G-; T _j = 25 °C; <u>Fig. 9</u> | - | - | 5 | mA |
| | | V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 9</u> | - | - | 5 | mA |
| ΙL | latching current | V _D = 12 V; I _G = 0.1 A; T2+ G-; T _j = 25 °C; <u>Fig. 10</u> | - | - | 6 | mA |
| | | V_D = 12 V; I _G = 0.1 A; T2+ G+; T _j = 25 °C; <u>Fig. 10</u> | - | - | 9 | mA |
| | | V _D = 12 V; I _G = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 10</u> | - | - | 6 | mA |
| Ч | holding current | V _D = 12 V; T _j = 25 °C; <u>Fig. 11</u> | - | - | 6 | mA |
| V _T | on-state voltage | I _T = 2 A; T _j = 25 °C; <u>Fig. 12</u> | - | 1.2 | 1.5 | V |
| V _{GT} | gate trigger voltage | V _D = 12 V; I _T = 0.1 A; T _j = 25 °C; Fig. 13 | - | 0.7 | 1 | V |
| | | V _D = 400 V; I _T = 0.1 A; T _j = 125 °C; Fig. 13 | 0.25 | 0.4 | - | V |
| I _D | off-state current | V _D = 600 V; T _j = 125 °C | - | 0.1 | 0.5 | mA |
| Dynamic ch | naracteristics | · · · | | 1 | | |
| dV _D /dt | rate of rise of off-state voltage | V_{DM} = 402 V; T _j = 125 °C; (67% of V_{DRM}); exponential waveform; gate open circuit | 20 | - | - | V/µs |
| dl _{com} /dt | rate of change of commutating current | V_D = 400 V; T _j = 125 °C; I _{T(RMS)} = 1 A; dV _{com} /dt = 0.1 V/µs; gate open circuit | 5 | - | - | A/ms |
| | | $V_D = 400 \text{ V}; \text{ T}_j = 125 \text{ °C}; \text{ I}_{T(RMS)} = 1 \text{ A};$ $dV_{com}/dt = 20 \text{ V}/\mu \text{s}; \text{ (snubberless condition); gate open circuit}$ | 1 | - | - | A/ms |

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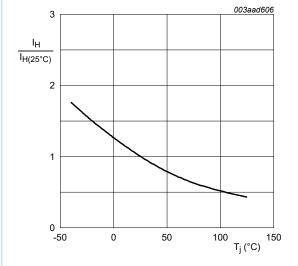
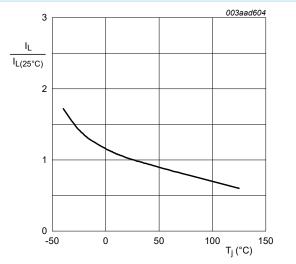
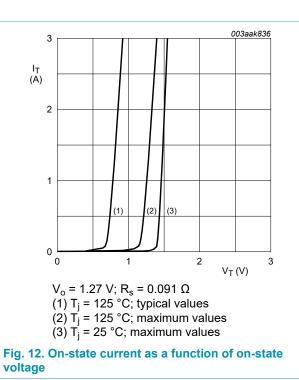


Fig. 11. Normalized holding current as a function of junction temperature

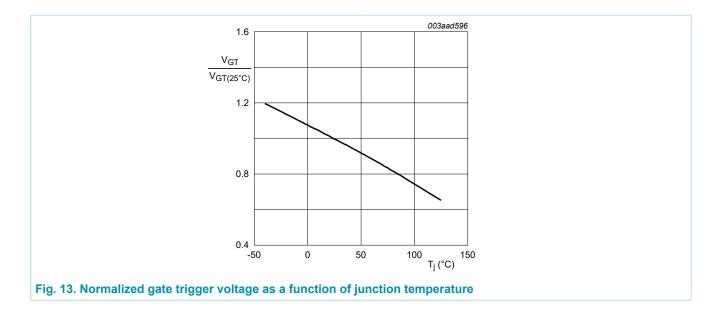






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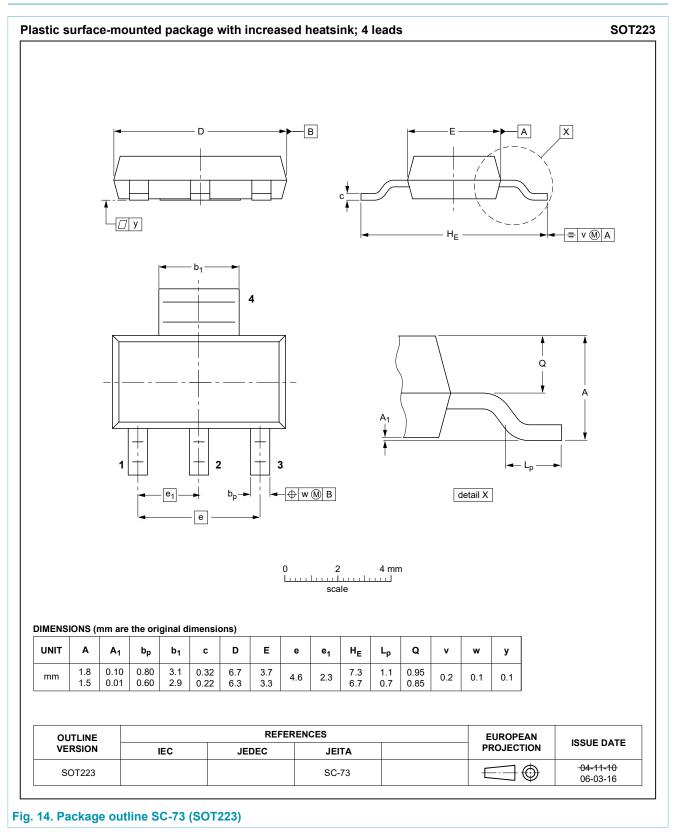
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10. Package outline



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11. Legal information

Data sheet status

| Document status [1][2] | Product status [<u>3]</u> | Definition |
|--------------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

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